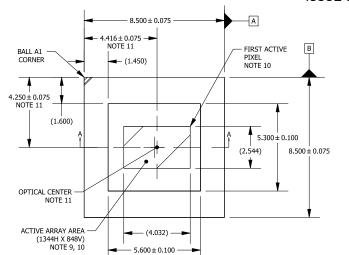
IBGA130 8.5x8.5

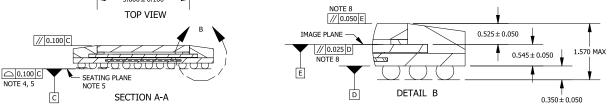
CASE 503BK ISSUE C

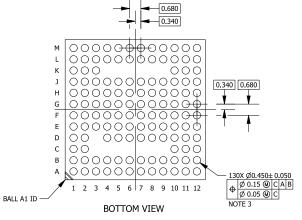
DATE 14 FEB 2020

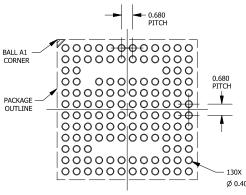


NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
- 2. CONTROLLING DIMENSION: MILLIMETERS [mm].
- 3. SOLDER BALL DIAMETER IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER PARALLEL TO DATUM C.
- 4. COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE SOLDER BALLS.
- 5. DATUM C, THE SEATING PLANE IS DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
- 6. GLASS: 0.400 THICKNESS; REFRACTIVE INDEX = 1.52; AR COATING R<1% 420-850nm (EACH SIDE).
- 7. AIR GAP BETWEEN GLASS AND PIXEL ARRAY: 0.125 THICKNESS.
- 8. PARALLELISM APPLIES ONLY TO THE ACTIVE ARRAY.
- 9. MAXIMUM ROTATION OF ACTIVE ARRAY RELATIVE TO DATUMS A AND B IS \pm 1°.
- 10. REFER TO THE DEVICE DATA SHEET FOR TOTAL PIXEL ARRAY AND FIRST ACTIVE PIXEL DEFINITIONS.
- 11. OPTICAL CENTER RELATIVE TO PACKAGE CENTER (X, Y) = (0.166, 0.000).
- 12. PACKAGE CENTER (X, Y) = (0.000, 0.000)



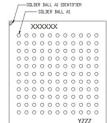




RECOMMENDED MOUNTING FOOTPRINT*

*FOR ADDITIONAL INFORMATION ON OUR Pb-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ON SEMICONDUCTOR SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERRM/D.

GENERIC MARKING DIAGRAM*



XXXX = Specific Device Code

Y = Year

ZZZ = Lot Traceability

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

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DESCRIPTION:	IBGA130 8.5X8.5		PAGE 1 OF 1

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